

## HUAWEI EM820W HSPA+ PC Embedded Module

## **Hardware Guide**

lssue 01 Date 2010-12-31 Huawei Technologies Co., Ltd. provides customers with comprehensive technical support and service. For any assistance, please contact our local office or company headquarters.

### Huawei Technologies Co., Ltd.

Huawei Industrial Base, Bantian, Longgang, Shenzhen 518129, People's Republic of China

Tel: +86-755-28780808 Global Hotline: +86-755-28560808 Website: www.huawei.com

#### E-mail: mobile@huawei.com

Please refer color and shape to product. Huawei reserves the right to make changes or improvements to any of the products without prior notice.

#### Copyright © Huawei Technologies Co., Ltd. 2009. All rights reserved.

No part of this document may be reproduced or transmitted in any form or by any means without prior written consent of Huawei Technologies Co., Ltd.

The product described in this manual may include copyrighted software of Huawei Technologies Co., Ltd and possible licensors. Customers shall not in any manner reproduce, distribute, modify, decompile, disassemble, decrypt, extract, reverse engineer, lease, assign, or sublicense the said software, unless such restrictions are prohibited by applicable 1900 or such actions are approved by respective copyright holders under licenses.

#### **Trademarks and Permissions**

HUAWEI, HUAWEI, and State trademarks or registered trademarks of Huawei Technologies Co., Ltd.

Other trademarks, product, service and company names mentioned are the property of their respective owners.

#### Notice

Some features of the product and its accessories described herein rely on the software installed, capacities and settings of local network, and may not be activated or may be limited by local network operators or network service providers, thus the descriptions herein may not exactly match the product or its accessories you purchase.

Huawei Technologies Co., Ltd reserves the right to change or modify any information or specifications contained in this manual without prior notice or obligation.

#### NO WARRANTY

THE CONTENTS OF THIS MANUAL ARE PROVIDED "AS IS". EXCEPT AS REQUIRED BY APPLICABLE L900, NO WARRANTIES OF ANY KIND, EITHER EXPRESS OR IMPLIED, INCLUDING BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE, ARE MADE IN RELATION TO THE ACCURACY, RELIABILITY OR CONTENTS OF THIS MANUAL.

TO THE MAXIMUM EXTENT PERMITTED BY APPLICABLE LAW, IN NO CASE SHALL HUAWEI TECHNOLOGIES CO., LTD BE LIABLE FOR ANY SPECIAL, INCIDENTAL, INDIRECT, OR CONSEQUENTIAL DAMAGES, OR LOST PROFITS, BUSINESS, REVENUE, DATA, GOODWILL OR ANTICIPATED SAVINGS.

#### Import and Export Regulations

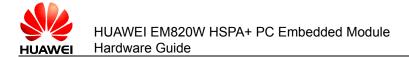
Customers shall comply with all applicable export or import I900 and regulations and will obtain all necessary governmental permits and licenses in order to export, re-export or import the product mentioned in this manual including the software and technical data therein.



## **About This Document**

## History

| Version | Date       | Chapter | Descriptions |
|---------|------------|---------|--------------|
| 01      | 2010-12-31 |         | Creation     |



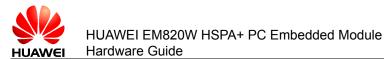
## Contents

| 1 Introduction                              | 1   |
|---|-----|
| 1.1 Overview                                | 1   |
| 2 Overall Description                       | 2   |
| 2.1 About This Chapter                      | 2   |
| 2.2 Function Overview                       | 2   |
| 2.3 Circuit Block Diagram                   | 3   |
| 2.4 Application Block Diagram               | 4   |
| 3 Description of the Application Interfaces | 5   |
| 3.1 About This Chapter                      | 5   |
| 3.2 Mini PCI Express Interface              | 5   |
| 3.3 Power Sources and Grounds               | 8   |
| 3.4 Power Supply Time Sequence              | 8   |
| 3.5 USB Signals                             | 9   |
| 3.6 USIM Signals                            | 10  |
| 3.6.1 USIM Interface Schematic Reference    | 10  |
| 3.6.2 Design Guide                          | .11 |
| 3.6.3 Certification Test                    | 13  |
| 3.7 W_DISABLE# Signal                       | 14  |
| 3.8 LED_WWAN# Signal                        | 14  |
| 3.9 WAKE_NB_N Signal                        |     |
| 3.10 NC Pins                                | 16  |
| 4 RF Specifications                         | 17  |
| 4.1 Operating Frequencies                   | 17  |
| 4.2 Conducted RF Measurement                | 17  |
| 4.2.1 Test Environment                      | 17  |
| 4.2.2 Test Standards                        | 18  |
| 4.3 Conducted Rx Sensitivity and Tx Power   | 18  |
| 4.3.1 Conducted Receive Sensitivity         | 18  |
| 4.3.2 Conducted Transmit Power              | 19  |
| 4.4 Antenna Design Requirements             | 20  |

Huawei Proprietary and Confidential Copyright © Huawei Technologies Co., Ltd.



| 4.4.1 Antenna Design Indicators                         | 20 |
|---|----|
| 4.4.2 Interference                                      | 23 |
| 4.4.3 GSM/WCDMA Antenna Requirements                    | 23 |
| 4.4.4 Radio Test Environment                            | 24 |
| 4.5 Design Recommendations                              | 25 |
| 4.5.1 Recommendations for Designing the Module Antennas | 25 |
| 4.6 ESD Protection for the Antenna Interface            |    |
| 5 Electrical and Reliability Features                   | 28 |
| 5.1 About This Chapter                                  |    |
| 5.2 Extreme Working Conditions                          |    |
| 5.3 Working and Storage Temperatures and Humidity       |    |
| 5.4 Electrical Criteria of Application Interfaces       | 29 |
| 5.5 Power Supply Features                               | 30 |
| 5.5.1 Power Supply                                      | 30 |
| 5.5.2 Power Consumption                                 | 30 |
| 5.6 Reliability Features                                | 33 |
| 5.7 EMC and ESD Features                                | 35 |
| 6 Mechanical Specifications                             |    |
| 6.1 Dimensions and Interfaces                           | 36 |
| 6.1.1 Dimensions and Interfaces of EM820W               | 36 |
| 6.2 Dimensions of the Mini PCI Express Connector        | 36 |
| 6.3 Specification Selection for Fasteners               | 37 |
| 6.3.1 Installing the EM820W on the Main Board of PC     | 37 |
| 6.3.2 Romoving the EM820W from the Main Board of PC     | 39 |
| 7 Appendix A Circuits of Typical Interfaces             | 40 |
| 8 Appendix B Acronyms and Abbreviations                 | 41 |



## Tables

| Table 2-1 Feature  | 2  |
|--|----|
| Table 3-1 Pin definitions of the Mini PCI-E Interface                                      | 5  |
| Table 3-2 Power and ground specifications  | 8  |
| Table 3-3 USB pins   | 9  |
| Table 3-4 USB signal DC characteristics  | 9  |
| Table 3-5 USIM pins1   | 0  |
| Table 3-6 SIM RST requirements         1   | 2  |
| Table 3-7 SIM CLK requirements         1   | 2  |
| Table 3-8 SIM IO requirements         1  | 3  |
| Table 3-9 W_DISABLE_N signal1  | 4  |
| Table 3-10 Radio operational states         1  | 4  |
| Table 3-11 LED_WWAN signal 1   | 15 |
| Table 4-1 RF bands 1   | 17 |
| Table 4-2 EM820W conducted Rx sensitivity         1  | 8  |
| Table 4-3 EM820W conducted Tx power         1  | 9  |
| Table 4-4 Isolation between the master antenna and the Wi-Fi antenna                       | 21 |
| Table 4-5 GSM/WCDMA antenna requirements         2   | 23 |
| Table 5-1 Working and storage temperatures and humidity for the EM820W module              | 29 |
| Table 5-2 Electrical features of application interfaces         2                          | 29 |
| Table 5-3 Power requirements   | 30 |
| Table 5-4 DC power consumption (HSPA/WCDMA)         3                                      | 30 |
| Table 5-5 DC power consumption (GSM/GPRS/EDGE)         3                                   | 31 |
| Table 5-6 DC power consumption(Idle and Suspend)         3                                 | 33 |
| Table 5-7 Test conditions and results of the mechanical reliability of the EM820W module.3 | 33 |



## Figures

| Figure 2-1 Circuit block diagram of the EM820W module                   | 4  |
|---|----|
| Figure 2-2 Application block diagram of the EM820W module               | 4  |
| Figure 3-1 HUAWEI EM820W power supply time sequence.                    | 9  |
| Figure 3-2 USIM interface schematic on PC                               | 11 |
| Figure 3-3 Pin definition of the SIM card Socket                        | 11 |
| Figure 3-4 LED_WWAN# signal reference circuit diagram                   | 15 |
| Figure 3-5 LED typical electro-optical characteristics curves           | 16 |
| Figure 4-1 SATIMO microwave testing chamber                             | 25 |
| Figure 4-2 Recommended antenna positions                                | 26 |
| Figure 4-3 ESD protection circuit recommended for the antenna interface | 27 |
| Figure 6-1 Dimensions of the EM820W                                     | 36 |
| Figure 6-2 Dimensions of the Mini PCI Express connector                 | 37 |
| Figure 7-1 Circuits of typical interfaces in the EM820W module          | 40 |





## 1.1 Overview

This document describes the hardware application interfaces and air interfaces that are provided when the Huawei EM820W HSPA+ PC Embedded module (hereinafter referred to as the EM820W module) is used.

This document helps you to understand the interface specifications, electrical features, and related product information of the EM820W module. To facilitate its use in different fields, relevant development guides document are also provided with the module, which can be obtained through Huawei website.





# **2** Overall Description

## 2.1 About This Chapter

This chapter gives a general description of the EM820W module and provides:

- Function Overview
- Circuit Block Diagram
- Application Block Diagram

## 2.2 Function Overview

#### Table 2-1 Feature

| Feature                                       | Description  |  |  |
|---|--|--|--|
| Working bands                                 | GSM/GPRS/EDGE 850/900/1800/1900 (MHz)<br>HSPA+/HSUPA/HSDPA/WCDMA 2100/1900/900/850 (MHz) |  |  |
| Working                                       | Normal working temperature: -10°C to +55°C   |  |  |
| temperature                                   | Extreme working temperatures: –20°C to –10°C and +55°C to +70°C                          |  |  |
| Ambient<br>temperature for<br>storage         | –40°C to 85°C  |  |  |
| Power voltage                                 | 3.3 V±9 %(3.3 V is recommended)  |  |  |
| AT commands                                   | See the HUAWEI EM820W HSPA+ PC Embedded Module Software Guide Specification.             |  |  |
| Application<br>interface (52pin<br>Mini PCI-E | One standard Subscriber Identity Module (SIM) card interface (3 V or 1.8 V)              |  |  |
| interface)                                    | USB 2.0 (high speed)   |  |  |
|   | WAKE#: Wake up signal  |  |  |

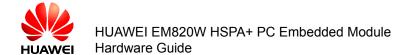


| Feature   | Description   |  |  |  |
|---|---|--|--|--|
|   | W_Disable#: for turning on/off the RF signal.   |  |  |  |
|   | LED_WWAN#: Active-low LED signal indicating the state of the card                             |  |  |  |
|   | Power Interface   |  |  |  |
|   | New message alert, receiving and sending text messages  |  |  |  |
| SMS   | Management of text messages: read messages, delete messages, storage status, and message list |  |  |  |
|   | Support for the protocol data unit (PDU) mode   |  |  |  |
|   | GSM CS: 9.6/14.4 kbps   |  |  |  |
|   | GPRS/EDGE: Multi-slot Class 12, Class B   |  |  |  |
| Data services   | WCDMA CS: UL 64kbps/DL 64kbps   |  |  |  |
|   | WCDMA/HSDPA PS: UL384kbps/DL3.6Mbps, HSDPA Category 6, 8, 9, 10, 12, 14                       |  |  |  |
|   | HSPA+ Rel7  |  |  |  |
| Physical<br>features  | Dimensions (L × W × H): 50.95 mm × 30 mm × 4.5 mm<br>Weight: < 15 g                           |  |  |  |
| Certification<br>information Restriction of the use of certain Hazardous Substances (<br>European Conformity (CE), Federal Communications<br>Commission (FCC) |   |  |  |  |

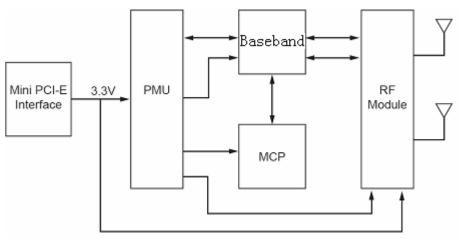
## 2.3 Circuit Block Diagram

Figure 2-1 shows the circuit block diagram of the EM820W module. The application block diagram and major functional units of the EM820W module contain the following parts:

- Mobile data modem
- Power management
- Multi-chip package (MCP) memory
- Radio frequency (RF) transceiver
- RF front-end modules
- Receive filter

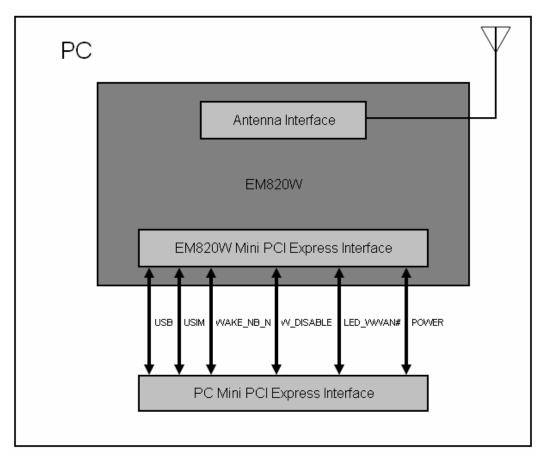






## 2.4 Application Block Diagram







## **3** Description of the Application Interfaces

## 3.1 About This Chapter

This chapter mainly describes the external application interfaces of the EM820W module, including:

- Mini PCI Express Interface
- Power Sources and Grounds
- Power Supply Time Sequence
- USB Signals
- USIM Signals
- W\_DISABLE# Signal
- LED\_WWAN# Signal
- WAKE\_NB\_N Signal
- NC Pins

## 3.2 Mini PCI Express Interface

The EM820W has a standard Mini PCI Express interface, which consists of several major signals, as shown in the following table.

| Definition of the EM820W Mini PCI Express pins |  |                           |   |                        |  |
|--|--|---------------------------|---|------------------------|--|
| Pin<br>No.                                     | Mini PCI<br>Express<br>Standard<br>Description | HUAWEI Pin<br>Description | Additional<br>Description   | Direction to<br>Module |  |
| 1  | WAKE#  | WAKE_NB_N                 | Open collector active<br>low signal. This signal<br>is used to wake up the<br>host. | Output                 |  |

Table 3-1 Pin definitions of the Mini PCI-E Interface



| Definition of the EM820W Mini PCI Express pins |  |                           |   |                        |  |
|--|--|---------------------------|---|------------------------|--|
| Pin<br>No.                                     | Mini PCI<br>Express<br>Standard<br>Description | HUAWEI Pin<br>Description | Additional<br>Description                     | Direction to<br>Module |  |
| 2  | 3.3Vaux  | VCC_3V3                   | 3.3 V DC supply rails from the PC side.       | Input                  |  |
| 3  | COEX1  | NC                        | Not connected.                                | -                      |  |
| 4  | GND  | GND                       | Mini Card ground.                             | -                      |  |
| 5  | COEX2  | NC                        | Not connected.                                | -                      |  |
| 6  | 1.5 V  | NC                        | Not connected.                                | -                      |  |
| 7  | CLKREQ#  | NC                        | Not connected.                                | -                      |  |
| 8  | UIM_PWR  | UIM_PWR                   | Power source for the external UIM/SIM card.   | Output                 |  |
| 9  | GND  | GND                       | Mini Card ground.                             | -                      |  |
| 10   | UIM_DATA                                       | UIM_DATA                  | External UIM/SIM data signal.                 | Input/output           |  |
| 11   | REFCLK-  | NC                        | Not connected.                                | -                      |  |
| 12   | UIM_CLK  | UIM_CLK                   | External UIM/SIM clock signal.                | Output                 |  |
| 13   | REFCLK+  | NC                        | Not connected.                                | -                      |  |
| 14   | UIM_RESET                                      | UIM_RESET                 | External UIM/SIM Output reset signal.         |                        |  |
| 15   | GND  | GND                       | Mini Card ground.                             | -                      |  |
| 16   | UIM_Vpp  | NC                        | Not connected.                                | -                      |  |
| 17   | Reserved                                       | NC                        | Not connected.                                | -                      |  |
| 18   | GND  | GND                       | Mini Card ground.                             | -                      |  |
| 19   | Reserved                                       | NC                        | Not connected.                                | -                      |  |
| 20   | W_DISABLE#                                     | W_DISABLE_N               | For ending the Input wireless communications. |                        |  |
| 21   | GND  | GND                       | Mini Card ground.                             | -                      |  |
| 22   | PERST#   | NC                        | Not connected.                                | -                      |  |
| 23   | PERn0  | NC                        | Not connected.                                | -                      |  |
| 24   | 3.3Vaux  | VCC_3V3                   | 3.3V DC supply rail from the PC side.         | Input                  |  |

Huawei Proprietary and Confidential Copyright © Huawei Technologies Co., Ltd.



| Definition of the EM820W Mini PCI Express pins |  |                           |  |                        |  |
|--|--|---------------------------|--|------------------------|--|
| Pin<br>No.                                     | Mini PCI<br>Express<br>Standard<br>Description | HUAWEI Pin<br>Description | Additional<br>Description                                      | Direction to<br>Module |  |
| 25   | PERp0  | NC                        | Not connected.   | -                      |  |
| 26   | GND  | GND                       | Mini Card ground.  | -                      |  |
| 27   | GND  | GND                       | Mini Card ground.  | -                      |  |
| 28   | 1.5 V  | NC                        | Not connected.   | -                      |  |
| 29   | GND  | GND                       | Mini Card ground.  | -                      |  |
| 30   | SMB_CLK  | NC                        | Not connected.   | -                      |  |
| 31   | PETn0  | NC                        | Not connected.   | -                      |  |
| 32   | SMB_DATA                                       | NC                        | Not connected.   | -                      |  |
| 33   | PETp0  | NC                        | Not connected.   | -                      |  |
| 34   | GND  | GND                       | Mini Card ground.  | -                      |  |
| 35   | GND  | GND                       | Mini Card ground.  | -                      |  |
| 36   | USB_D-   | USB_D-                    | USB signal D   | Input/output           |  |
| 37   | GND  | GND                       | Mini Card ground.  | und                    |  |
| 38   | USB_D+   | USB_D+                    | USB signal D+.   | Input/output           |  |
| 39   | 3.3Vaux  | VCC_3V3                   | 3.3V DC supply rail from the PC side.                          | Input                  |  |
| 40   | GND  | GND                       | Mini Card ground.  | -                      |  |
| 41   | 3.3Vaux  | VCC_3V3                   | 3.3V DC supply rail from the PC side.                          | Input                  |  |
| 42   | LED_WWAN#                                      | LED_WWAN                  | Active-low LED signal Output indicating the state of the card. |                        |  |
| 43   | GND  | GND                       | Mini Card ground.  | -                      |  |
| 44   | LED_WLAN#                                      | NC                        | Not connected.   | -                      |  |
| 45   | Reserved                                       | NC                        | Not connected.   | -                      |  |
| 46   | LED_WPAN#                                      | NC                        | Not connected.   | -                      |  |
| 47   | Reserved                                       | NC                        | Not connected.   | -                      |  |
| 48   | 1.5 V  | NC                        | Not connected.   | -                      |  |
| 49   | Reserved                                       | NC                        | Not connected.   | -                      |  |



| Definit    | Definition of the EM820W Mini PCI Express pins |                           |                                       |                        |  |  |
|------------|--|---------------------------|---------------------------------------|------------------------|--|--|
| Pin<br>No. | Mini PCI<br>Express<br>Standard<br>Description | HUAWEI Pin<br>Description | Additional<br>Description             | Direction to<br>Module |  |  |
| 50         | GND  | GND                       | Mini Card Ground.                     | -                      |  |  |
| 51         | Reserved                                       | NC                        | Not connected.                        | -                      |  |  |
| 52         | 3.3Vaux  | VCC_3V3                   | 3.3V DC supply rail from the PC side. | Input                  |  |  |

## **3.3 Power Sources and Grounds**

The PCI Express Mini Card provides two power sources: one is 3.3 Vaux (+3.3 Vaux) and the other is 1.5 V (+ 1.5 V). For the EM820W, however, +3.3 Vaux is the only voltage supply that is available. The input voltage is  $3.3 \text{ V}\pm9\%$ , as specified by PCI Express Mini CEM Specifications 1.2.

Table 3-2 Power and ground specifications

| Name | Pins  | Minimum | Туре  | Maximum |
|------|---|---------|-------|---------|
| VCC  | 2, 24,39, 41, and 52  | 3.0 V   | 3.3 V | 3.6 V   |
| GND  | 4, 9, 15, 18, 21, 26, 27, 29, 34,<br>35, 37, 40, 43, and 50 | 0 V     |       |         |

#### 

To minimize the RF radiation through the power lines, it is suggested to add ceramic capacitors of 10pF and 100nF in the ground beside the Mini PCI Express connector on the host side.

## 3.4 Power Supply Time Sequence

Figure 3-1 shows the PCIE with 3.3 V voltage and USB D+ power supply time sequence.

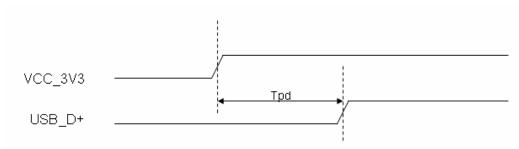


Figure 3-1 HUAWEI EM820W power supply time sequence.

| Parameter | Remarks                    | Time(Nominal value) | Unit |
|-----------|----------------------------|---------------------|------|
| Tpd       | Power Valid to USB D+ high | 3.24                | sec  |

## 3.5 USB Signals

The EM820W is compliant with USB 2.0 specification. It supports full-speed (12 Mbit/s) and high-speed (480 Mbit/s) modes when acting as a peripheral and supports low-speed, full-speed, and high-speed modes when acting as a host. The USB 2.0 specifications allow peripherals to support any one or more of these speeds. To ensure best performance, the PC USB host controller should support high-speed mode when using the EM820W USB high-speed mode.

#### Table 3-3 USB pins

| Name   | Pin | Description        | Direction to Module |
|--------|-----|--------------------|---------------------|
| USB D- | 36  | USB data signal D- | Input/output        |
| USB D+ | 38  | USB data signal D+ | Input/output        |

#### 

To minimize the RF radiation through the PCI-E interface, you can add a 33 pF ceramic capacitor in the ground on every pin of the PCI-E on the host side except USB D+/D-.

The USB interface is powered directly from the 3.3 V supply. The USB input/output lines are compatible with the USB2.0 3.3 V signal specifications.

| Table 3-4 USB sig | gnal DC characteristics |
|-------------------|-------------------------|
|-------------------|-------------------------|

| VOHmin | VOLmax | VIHmin | VILmax |
|--------|--------|--------|--------|
| 2.8 V  | 0.3 V  | 2 V    | 0.8 V  |



The high-speed signal characteristics are in accordance with the Eye Pattern Templates of the USB2.0 signal specification.

## 3.6 USIM Signals

The USIM is a smart card for UMTS/GSM cellular applications. The USIM provides the required subscription information to allow mobile equipment to attach to a GSM or UMTS network. The USIM also provides the subscriber's verification procedures as well as authentication methods for network authentication during the process of attaching to a network.

#### Table 3-5 USIM pins

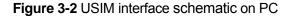
| Pin | Name      | Description                            | Direction to Module |
|-----|-----------|--|---------------------|
| 8   | UIM_PWR   | Power source for the external UIM/SIM. | Output              |
| 10  | UIM_DATA  | External UIM/SIM data signal.          | Input/output        |
| 12  | UIM_CLK   | External UIM/SIM clock signal.         | Output              |
| 14  | UIM_RESET | External UIM/SIM reset signal.         | Output              |

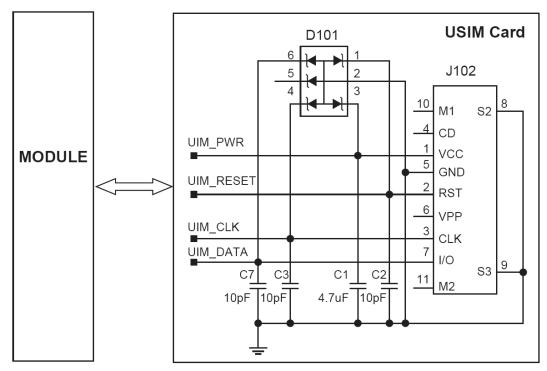
#### 

It is recommended that the SIM card is inserted only after the power supply of the module is disconnected; otherwise the SIM card may get destroyed.

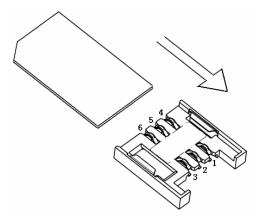
#### 3.6.1 USIM Interface Schematic Reference

There is no SIM card interface circuit in the EM820W module, and users need to add the USIM interface circuit. Figure 3-2 shows the definition of interface signals and the typical USIM interface schematic.





#### Figure 3-3 Pin definition of the SIM card Socket



| pin1: | SIM_VCC   | pin4: | GND      |
|-------|-----------|-------|----------|
| pin2: | SIM_RESET | pin5: | NULL     |
| pin3: | SIM_CLK   | pin6: | SIM_DATA |

## 3.6.2 Design Guide

The USIM signals are connected to the Mini PCI Express card connector (the card edge connector) and pass through an EMI filtering and ESD protection circuit on the

|                       | Huawei Proprietary and Confidential       |
|-----------------------|---|
| Issue 01 (2010-12-31) | Copyright © Huawei Technologies Co., Ltd. |



module board before entering the EM820W processor. There is also an EMI filtering and ESD protection circuit between the SIM card interface and the Mini PCI interface on the user's board.

• Power supply

The SIM card interface is powered by an internal LDO regulator of EM820W. The default value of this regulator is 2.85 V. The power of the regulator is programmable in the range of 1.5 V to 3.05 V and is expected to be set to 3.0 V or 1.8 V.

Modem signals

After a power-on or reset, the USIM signals are activated to detect if a SIM card is present and to initialize it if it exists. Once a SIM card has been detected and initialized, the interface is always on. However, the clock signal is only activated when data is actually being transmitted. The USIM signals from the module are connected to the level translators, and then to the Mini Card host connector.

- The UIM\_DETECT pin is optional, depending on whether this function is required.
- For UIM\_DATA, it does not need to add a pull-up resistor, because it has been pulled up to UIM\_PWR with a 15 kΩ resistor on the module, in compliance with the ISO/IEC 7816-3.
- For UIM\_PWR, it is recommended to add an additional decoupling capacitor ranging from 1uF to 10uF, and to place a 10pF capacitor on each of the signals such as UIM\_RST, UIM\_CLK and UIM\_DATA.

These levels exceed those required in ISO/IEC 7816-3.

SIM signals

The following data is taken from the ETSI standard Specification of the 3 Volt Subscriber Identity Module - Mobile Equipment (SIM-ME) interface (GSM 11.12 version 4.3.1).

#### Table 3-6 SIM RST requirements

| RST             | Minimum | Maximum |
|-----------------|---------|---------|
| V <sub>IL</sub> | 0       | 0.2Vcc  |
| V <sub>IH</sub> | 0.7Vcc  | Vcc     |

#### Table 3-7 SIM CLK requirements

| CLK             | Minimum | Maximum |
|-----------------|---------|---------|
| V <sub>IL</sub> | 0       | 0.2Vcc  |
| V <sub>IH</sub> | 0.7Vcc  | Vcc     |



#### Table 3-8 SIM IO requirements

| Ю               | Minimum | Maximum |
|-----------------|---------|---------|
| V <sub>IL</sub> | 0       | 0.4     |
| V <sub>IH</sub> | 0.7Vcc  | Vcc     |
| V <sub>OL</sub> | -0.3    | 0.2 Vcc |
| V <sub>OH</sub> | 0.7 Vcc | Vcc+0.3 |

#### 

The V<sub>OL</sub>max of 0.45 V for the output is specified at an output current of 3 mA whereas the V<sub>IL</sub>max of 0.4 V for the SIM IO input is specified at an input current of 1 mA. With the smaller current drive, the output voltage would be driven lower than the stated maximum value.

#### ESD protection

Since the SIM is a CMOS device, ESD protection devices should be placed near the SIM connector to provide protection before connecting to the module. In addition, all the SIM interface signals should be bypassed with a 10 pF capacitor. The used ESD device (PESD3V3L5UY, NXP) in Figure 3-2 is a low capacitance 5-fold ESD protection diode arrays in SOT363 package.

Clock frequency

The SIM must support clock frequencies between 1 MHz and 4 MHz. (The Mini Card can be programmed to generate a clock of 1.625 MHz, 2.6 MHz, or 3.25 MHz.)

• Routing recommendations

The SIM interface signals consist of four signals that are UIM\_PWR, UIM\_RST, UIM\_CLK, and UIM\_DATA (UIM\_Vpp is neither connected nor used in many applications). Due to the relatively low clock frequencies involved, the concern is not the degradation of the SIM signals but that of routing of the SIM interface signals through areas considered to be of high risk for RF noise coupling (crosstalk and RF contamination), which can desensitize the radio circuitry. The general guidelines that should be followed are listed as follows:

- It is recommended that these signals should be routed over a continuous ground plane.
- SIM interface signals should not be routed near high transient signals (power supply chokes and DC/DC switching FETs).
- Prevent routing of these signals near output connectors.
- Keep SIM interface signals isolated from other signals. 2x width spacing (1.5x min) between SIM interface signals and all other signal routing is recommended.

#### 3.6.3 Certification Test

Using test equipment simulates a (U)SIM card to test U(SIM) protocol in GCF or PTCRB test, If some test. If you encounter some issues during SIM/USIM test, please contact Huawei for more details.



## 3.7 W\_DISABLE# Signal

The W\_DISABLE# signal is provided to allow users to disable wireless communications add-in cards. When the W\_DISABLE# signal is asserted, all radios should be disabled. When the W\_DISABLE# signal is not asserted, the radio may transmit signals if it is not disabled by other means such as software.

The W\_DISABLE# signal is an active low signal with internal 100 k $\Omega$  pull-up resistor that disables radio operation when being asserted (driven low) by the system.

The combination of the software state and W\_DISABLE# assertion state must be determined before the normal operation is resumed. Table 3-10 lists this requirement for W\_DISABLE# and the software control setting. For example, the radio RF operation remains disabled unless both the hardware and software are set to enable the RF features of the card.

Table 3-9 W\_DISABLE\_N signal

| Pins | Name        | Description                   | Direction to Module |
|------|-------------|-------------------------------|---------------------|
| 20   | W_DISABLE_N | Close wireless communications | Input               |

| Table 3-10 Radio | operationa | states |  |
|------------------|------------|--------|--|
|                  |            |        |  |

| W_DISABLE# | SW Control Setting* | Radio Operation |
|------------|---------------------|-----------------|
| High       | Enabled             | Enabled         |
| High       | Disabled            | Disabled        |
| Low        | Enabled             |                 |
| Low        | Disabled            |                 |

\* This control setting is implementation specific; this column represents the collective intention of the host software to manage radio operation.

#### 

- If you do not turn off the radio manually, the radio will be on when the module is powered on.
- End users need to turn off the radio in some situations such as when being on an airplane.
- According to Mini-PCIE specification, the radio must be turned off through hardware or software. Nearly all PC companies comply with this specification.

## 3.8 LED\_WWAN# Signal

The LED\_WWAN signal of the EM820W can allow the voltage of 3.3 V and absorb the current from 5 mA to 40 mA. According to the given circuit, in order to reduce the current of the LED, a resistance of 1 k $\Omega$  must be placed in series with the LED.

Issue 01 (2010-12-31)

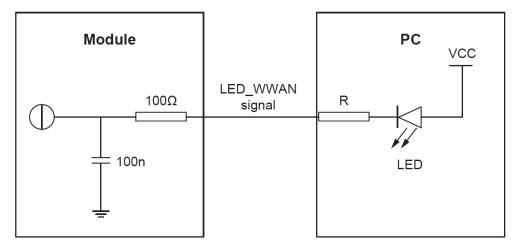


#### Table 3-11 LED\_WWAN signal

| Pins | Name     | Description  | Additional<br>Description   | Direction to<br>Module |
|------|----------|--|-----------------------------|------------------------|
| 42   | LED_WWAN | Active-low LED signal indicating the status of the module. | L: Light on<br>H: Light off | Output                 |

This signal is used to display the state of WWAN. The reference circuit diagram is shown in the following figure.

| Figure 3-4 LED   | WWAN# signal reference circuit diagra | m |
|------------------|---------------------------------------|---|
| I Iguile & I LLD |                                       |   |



#### 

Normally, when the HUAWEI module is enabled, the LED is on, and when disabled, the LED is off. The wink mode of the LED can be customized according to the requirement of the client.

For resistance of R placed on PC, choose the value that satisfies the following equation:

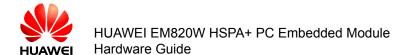
IF\*R+VF+IF\*100 =VCC

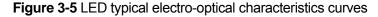
VF: Forward Voltage

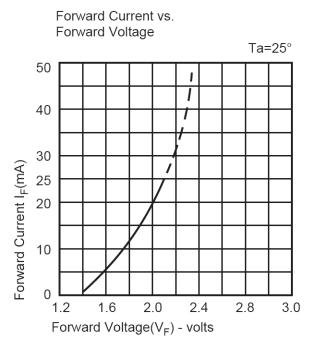
IF: Forward current

Take the LED 19-213/GVC-AMNB/3T as an example (its manufacturer is Everlight Electronics., Ltd. and the website is http://www.everlight.com). Figure 3-5 shows its I<sub>F</sub>-V<sub>F</sub> curves. If VCC is 3.3 V and the desired current through the LED I<sub>F</sub> is 3 mA, then the voltage of the LED V<sub>F</sub> is 1.5 V. According to I<sub>F</sub>-V<sub>F</sub> curves, the corresponding value for resistance of R is  $(3.3 - 0.003 \times 100 - 1.5) / 0.003 = 500 \Omega$ .

The brightness of the LED depends on the current value, and for most of the indicator lights the current between 2 mA to 5 mA is adequate.







## 3.9 WAKE\_NB\_N Signal

WAKE\_NB\_N (signal that the module uses to activate the PC)

Support software controls the signal (WAKE\_NB\_N) that the module uses to activate the PC. This signal is used for 3G module to wake up the host. It's designed as a OC gate, so it should be pulled up by the host and it's active-low.

## 3.10 NC Pins

The NC pins are not internally connected in the EM820W.



## **4 RF** Specifications

## **4.1 Operating Frequencies**

Table 4-1 shows the RF bands supported by EM820W.

#### Table 4-1 RF bands

| <b>Operating Band</b> | Тх            | Rx            |
|-----------------------|---------------|---------------|
| UMTS 2100 (Band I)    | 1920–1980 MHz | 2110–2170 MHz |
| UMTS 1900 (Band II)   | 1850–1910 MHz | 1930–1990 MHz |
| UMTS 900 (Band VIII)  | 880–915 MHz   | 925–960 MHz   |
| UMTS 850(Band V)      | 824–849MHz    | 869–894 MHz   |
| GSM 850               | 824–849 MHz   | 869–894 MHz   |
| GSM 900               | 880–915 MHz   | 925–960 MHz   |
| GSM 1800(DCS)         | 1710–1785 MHz | 1805–1880 MHz |
| GSM 1900(PCS)         | 1850–1910 MHz | 1930–1990 MHz |

## 4.2 Conducted RF Measurement

#### 4.2.1 Test Environment

- Test instrument: R&S CMU200
- Power supply: KEITHLEY 2306
- RF cable for testing:

L08-C014-350 of DRAKA COMTEQ or Rosenberger

Cable length: 29 cm



Compensation for WCDMA 850 MHz or 900 MHz: 0.6 dB

Compensation for WCDMA 2100 MHz or WCDMA 1900 MHz: 0.8 dB

#### 

The compensation for different frequency bands relates to the cable and the test environment. The instrument compensation needs to be set according to the actual cable conditions.

## 4.2.2 Test Standards

Huawei modules meet all 3GPP test standards relating to both 2G and 3G. Each module has passed stringent tests in the factory, thus the quality of the modules is guaranteed.

## 4.3 Conducted Rx Sensitivity and Tx Power

#### 4.3.1 Conducted Receive Sensitivity

The conducted receive sensitivity is a key parameter that indicates the receiver performance of EM820W. The conducted receive sensitivity means the weakest signal that the module at the antenna port can receive. The BER must meet the 3GPP protocol requirements in the case of the minimum signal.

The 3GPP Protocol Claim column in Table 4-2 lists the required minimum values, and the Test Value column lists the tested values of EM820W.

| Item       |                         | 3GPP Protocol | EM820W Test Value (dBm) |        |      |
|------------|-------------------------|---------------|-------------------------|--------|------|
|            |                         | Claim (dBm)   | Min                     | Туре   | Max  |
| GSM850     | GMSK(BER <2.43%)        | < -102        | -                       | -109   | -107 |
|            | 8PSK(MCS5,<br>BLER<10%) | < -98         | -                       | -103.5 | -101 |
| GSM900     | GMSK(BER <2.43%)        | < -102        | -                       | -109   | -107 |
|            | 8PSK(MCS5,<br>BLER<10%) | < -98         | -                       | -103.5 | -101 |
| GSM1800    | GMSK(BER <2.43%)        | < -102        | -                       | -109   | -107 |
|            | 8PSK(MCS5,<br>BLER<10%) | < -98         | -                       | -102.5 | -100 |
| GSM1900    | GMSK(BER <2.43%)        | < -102        | -                       | -109   | -107 |
|            | 8PSK(MCS5,<br>BLER<10%) | < -98         | -                       | -102.5 | -100 |
| Bandl (BER | <0.1%)                  | < -106.7      | -                       | -110   | -108 |

Table 4-2 EM820W conducted Rx sensitivity

Huawei Proprietary and Confidential Copyright © Huawei Technologies Co., Ltd.



| Item                 | 3GPP Protocol | EM820V | V Test Value (dBm) |      |
|----------------------|---------------|--------|--------------------|------|
|                      | Claim (dBm)   | Min    | Туре               | Max  |
| BandII (BER<0.1%)    | < -104.7      | -      | -110               | -108 |
| Band VIII (BER<0.1%) | < -103.7      | -      | -110               | -108 |
| Band V (BER<0.1%)    | < -104.7      | -      | -110               | -108 |

#### 

The test values are the average of some test samples.

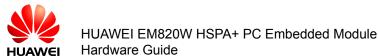
## 4.3.2 Conducted Transmit Power

The conducted transmit power is another indicator that measures the performance of EM820W. The conducted transmit power means the maximum power that the module tested at the antenna port can transmit. According to the 3GPP protocol, the required transmit power varies with the power class.

Table 4-3 lists the required ranges of the conducted transmit power of EM820W. The tested values listed in the Test Value column must be within the range from the minimum power to the maximum power.

| Item            |                | 3GPP Protocol<br>Claim (dBm) | EM820W Test Value (dBm) |      |      |
|-----------------|----------------|------------------------------|-------------------------|------|------|
|                 |                |                              | Min                     | Туре | Max  |
| GSM850          | GMSK(1Tx Slot) | 31~35                        | 31.5                    | 32.5 | 33.5 |
|                 | 8PSK(1Tx Slot) | 24~30                        | 26                      | 27   | 28   |
| GSM900          | GMSK(1Tx Slot) | 31~35                        | 31.5                    | 32.5 | 33.5 |
|                 | 8PSK(1Tx Slot) | 24~30                        | 26                      | 27   | 28   |
| GSM1800         | GMSK(1Tx Slot) | 28~32                        | 28.5                    | 29.5 | 30.5 |
|                 | 8PSK(1Tx Slot) | 23~29                        | 25                      | 26   | 27   |
| GSM1900         | GMSK(1Tx Slot) | 28~32                        | 28.5                    | 29.5 | 30.5 |
|                 | 8PSK(1Tx Slot) | 23~29                        | 25                      | 26   | 27   |
| Band I(W21      | 00)            | 21~25                        | 22.5                    | 23.5 | 24.5 |
| Band II(W1900)  |                | 21~25                        | 22.5                    | 23.5 | 24.5 |
| Band VIII(W900) |                | 21~25                        | 22.5                    | 23.5 | 24.5 |
| Band V(W85      | 50)            | 21~25                        | 22.5                    | 23.5 | 24.5 |

#### Table 4-3 EM820W conducted Tx power



## 4.4 Antenna Design Requirements

#### 4.4.1 Antenna Design Indicators

#### **Antenna Efficiency**

Antenna efficiency is the ratio of the input power to the radiated or received power of an antenna. The radiated power of an antenna is always lower than the input power due to the following losses: return loss, material loss, and coupling loss. The efficiency of an antenna relates to its electrical dimensions. To be specific, the antenna efficiency increases with the electrical dimensions. In addition, the transmission cable from the antenna port of the EM820W to the antenna is also part of the antenna. The cable loss increases with the cable length and the frequency. It is recommended that the cable loss should be as low as possible, for example, U.FL-LP-088 made by HRS.

The following antenna efficiency (free space) is recommended for the EM820W on a laptop to ensure high radio performance of the EM820W:

- Efficiency of the master antenna > 40% (-4 dB)
- Efficiency of the slave antenna > 40% (-4 dB)
- Efficiency of the GPS antenna > 50% (-3 dB)
- Efficiency of the Wi-Fi antenna > 40% (-4 dB)

#### Isolation

For a wireless device with multiple antennas, the power of different antennas is coupled with each other. Antenna isolation is used to measure the power coupling. The power radiated by an antenna might be received by an adjacent antenna, which decreases the antenna radiation efficiency and affects the running of other devices. To avoid this problem, evaluate the antenna isolation as sufficiently as possible at the early stage of antenna design.

Antenna isolation depends on the following factors:

- Distance between antennas
- Antenna type
- Antenna direction

The master antenna must be placed as near as possible to the EM820W to minimize the cable length. The slave antenna needs to be installed perpendicularly to the master antenna. The slave antenna can be placed farther away from the EM820W. Antenna isolation can be measured with a two-port vector network analyzer.

The following antenna isolation is recommended for the antennas on laptops:

- Isolation between master and slave antennas < -12 dB</li>
- Isolation between the master antenna and the GPS antenna < -15 dB</li>
- Isolation between the slave antenna and the Wi-Fi antenna < -15 dB</li>

If a Wi-Fi module is installed on the laptop, the following measures must be taken to reduce mutual influence between the data card module and the Wi-Fi module:



- Adding a bandpass filter to the Wi-Fi channel to filter the WCDMA, GSM850, GSM900, DCS, and PCS signals
- Ensuring sufficient isolation between the master antenna of the data card module and the Wi-Fi antenna

Table 4-4 lists the requirements for the isolation between the master antenna and the Wi-Fi antenna in different frequency bands according to the interference suppression supported by the filter in different frequency bands.

| Frequency<br>Band | Transmit<br>Frequency | Conducted<br>Transmit<br>Power (dBm) | Ant<br>Isolator<br>(dB) | Wi-Fi Front End<br>Filter Attenuation<br>(dB) |
|-------------------|-----------------------|--------------------------------------|-------------------------|---|
| UMTS2100          | 1920–1980 MHz         | 24                                   | 11                      | 34  |
| UMTS1900          | 1850–1910 MHz         | 24                                   | 11                      | 34  |
| UMTS850           | 824–849 MHz           | 24                                   | 10                      | 36  |
| UMTS900           | 880–915 MHz           | 24                                   | 10                      | 36  |
| GSM850            | 824–849 MHz           | 33                                   | 18                      | 36  |
| GSM900            | 880–915 MHz           | 33                                   | 18                      | 36  |
| DCS               | 1710–1785 MHz         | 30                                   | 17                      | 34  |
| PCS               | 1850–1910 MHz         | 30                                   | 17                      | 34  |

**Table 4-4** Isolation between the master antenna and the Wi-Fi antenna

#### S11 or VSWR

S11 (return loss) indicates the degree to which the input impedance of an antenna matches the reference impedance (50 ohm). S11 shows the resonance feature and impedance bandwidth of an antenna. Voltage standing wave ratio (VSWR) is another expression of S11. S11 relates to the antenna efficiency. S11 can be measured with a vector analyzer.

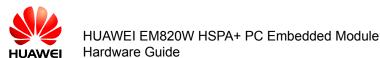
The following S11 values are recommended for the antennas on laptops:

- S11 of the master antenna < -6 dB
- S11 of the slave antenna < -6 dB
- S11 of the GSP antenna < -10 dB
- S11 of the Wi-Fi antenna < -10 dB</li>

#### Polarization

The polarization of an antenna is the orientation of the electric field vector that rotates with time in the direction of maximum radiation.

The linear polarization is recommended for the antennas on laptops.



#### **Envelope Correlation Coefficient**

The envelope correlation coefficient indicates the correlation between different antennas in a multi-antenna system (master antenna, diversity antenna, and MIMO antenna). The correlation coefficient shows the similarity of radiation patterns, that is, amplitude and phase, of the antennas. The ideal correlation coefficient of a diversity antenna system or a MIMO antenna system is 0. A small value of the envelope correlation coefficient between the master antenna and the slave antenna indicates a high diversity gain. The envelope correlation coefficient depends on the following factors:

- Distance between antennas
- Antenna type
- Antenna direction

The antenna correlation coefficient differs from the antenna isolation. Sufficient antenna isolation does not represent a satisfactory correlation coefficient. For this reason, the two indicators need to be evaluated separately.

For the antennas on laptops, the recommended envelope correlation coefficient between the master antenna and the diversity antenna is smaller than 0.5.

#### **Radiation Pattern**

The radiation pattern of an antenna reflects the radiation features of the antenna in the remote field region. The radiation pattern of an antenna describes the power or field strength of the radiated electromagnetic waves in various directions from the antenna. The power or field strength varies with the angular coordinates ( $\theta$  and  $\phi$ ), but is independent of the radial coordinates.

The radiation pattern of half wave dipole antennas is the best option for wireless terminals. The radiation pattern of half wave dipole antennas is omnidirectional in the horizontal plane, and the incident waves of base stations are often in the horizontal plane. For this reason, the reception is optimal.

To improve the performance of diversity antennas, it is recommended that the radiation pattern of the slave antenna be complementary with that of the master antenna.

The following radiation patterns are recommended for the antennas on laptops:

- Master antenna: omnidirectional
- Slave antenna: complementary with the radiation pattern of the master slave
- GPS antenna: omnidirectional
- Wi-Fi antenna: omnidirectional

#### Gain and Directivity

The radiation pattern of an antenna represents the field strength of the radiated electromagnetic waves in all directions, but not the power density that the antenna radiates in the specific direction. The directivity of an antenna, however, measures the power density that the antenna radiates.

Gain, as another important parameter of antennas, correlates closely to the directivity. The gain of an antenna takes both the directivity and the efficiency of the antenna



into account. The appropriate antenna gain prolongs the service life of relevant batteries.

The following antenna gain is recommended for antennas on laptops:

- Gain of the master antenna  $\leq$  3 dBi
- Gain of the slave antenna  $\leq$  3 dBi

#### 

- The antenna on a laptop consists of the antenna body and the relevant RF transmission cable. Take the RF transmission cable inside the laptop into account when measuring any of the preceding antenna indicators.
- Huawei cooperates with various antenna suppliers who are able to make suggestions on antenna design, for example, Amphenol, Skycross, Pulse etc.

#### **4.4.2 Interference**

Besides the antenna performance, the interference on the user board also affects the radio performance (especially the TIS) of the module. To guarantee high performance of the module, the interference sources on the user board must be properly controlled.

On the user board, there are various interference sources, such as the LCD, CPU, audio circuits, and power supply. All the interference sources emit interference signals that affect the normal operation of the module. For example, the module sensitivity can be decreased due to interference signals. Therefore, during the design, you need to consider how to lessen the effects of interference sources on the module. To lessen the effects of interference sources on the module, you can use an LCD with optimized performance, shield the LCD interference signals, shield the signal cable of the board, or design filter circuits.

Huawei is capable of making technical suggestions on radio performance improvement of the module.

#### 4.4.3 GSM/WCDMA Antenna Requirements

The antenna for EM820W must fulfill the following requirements:

| Table 4-5 GSIVI/WCDIVIA antenna requirements |
|--|
|  |

Table A E CONANCONAN antonna requirements

| GSM/WCDMA Antenna Requirements |   |  |
|--------------------------------|---|--|
| Frequency range                | Depending on the frequency band(s) provided by the network operator, the customer must use the most suitable antenna for that/those band(s) |  |



| GSM/WCDMA Antenr  | GSM/WCDMA Antenna Requirements |  |  |
|-------------------|--------------------------------|--|--|
| Bandwidth         | 70 MHz in GSM850               |  |  |
|                   | 80 MHz in GSM900               |  |  |
|                   | 170 MHz in DCS                 |  |  |
|                   | 140 MHz PCS                    |  |  |
|                   | 70 MHZ in WCDMA850             |  |  |
|                   | 80 MHz in WCDMA900             |  |  |
|                   | 140 MHz in WCDMA1900           |  |  |
|                   | 250 MHz in WCDMA2100 band      |  |  |
| Gain              | Gain < 3dBi                    |  |  |
| Impedance         | 50 Ohm                         |  |  |
| Input power       | > 33dBm(2 W) peak power in GSM |  |  |
|                   | > 24dBm Average power in WCDMA |  |  |
| VSWR absolute max | <= 10:1                        |  |  |
| VSWR recommended  | <= 2:1                         |  |  |

Furthermore, if the device is developed for US and/or Canada market, it must comply with the FCC and/or IC approval requirements:

This device is to be used only for mobile and fixed application. The antenna(s) used for this transmitter must be installed to provide a separation distance of at least 20 cm from all persons and must not be co-located or operating in conjunction with any other antenna or transmitter. End-Users must be provided with transmitter operation conditions for satisfying RF exposure compliance. OEM integrators must ensure that the end user has no manual instructions to remove or install the UC864-E/G/WD /WDU module. Antennas used for this OEM module must not exceed 3dBi gain for mobile and fixed operating configurations.

#### 4.4.4 Radio Test Environment

The antenna efficiency, antenna gain, radiation pattern, total radiated power (TRP), and TIS can be tested in a microwave testing chamber.

Huawei has a complete set of OTA test environment (SATIMO microwave testing chambers and ETS microwave testing chambers). The testing chambers are certified by professional organizations and are applicable to testing at frequencies ranging from 380 MHz to 6 GHz. The test items are described as follows:

#### **Passive Tests**

- Antenna efficiency
- Gain
- Pattern shape
- Envelope correlation coefficient

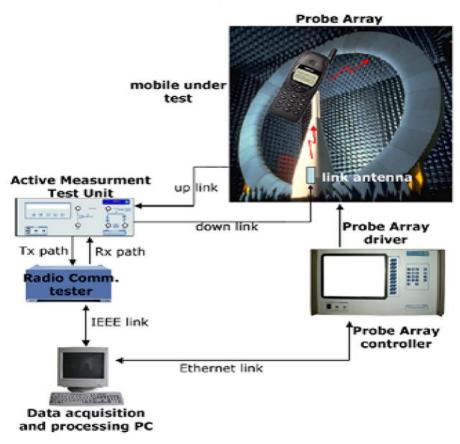


#### **Active Tests**

- TRP: GSM, WCDMA, CDMA, TD-SCDMA, and LTE systems
- TIS: GSM, WCDMA, CDMA, TD-SCDMA, and LTE systems

Figure 4-1 shows the SATIMO microwave testing chamber.

Figure 4-1 SATIMO microwave testing chamber

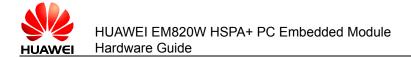


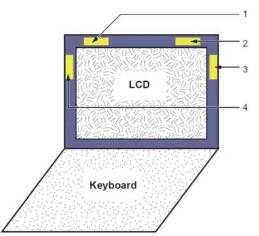
## 4.5 Design Recommendations

## 4.5.1 Recommendations for Designing the Module Antennas

The design recommendations are as follows:

- It is recommended that the module antennas are designed at the upper edge, left edge, or right edge of the laptop screen. Designing the antenna at the upper edge is better.
- Take the isolation and envelope correlation between the master antenna and the slave antenna into account when designing the antennas. Keep the slave antenna away from the master antenna as far as possible. Install the slave antenna perpendicularly to the master slave. See Figure 4-2, Install the master and slave antennas in positions 1 and 3 or 2 and 4 but not in positions 1 and 2 or 3 and 4.





#### Figure 4-2 Recommended antenna positions

- It is recommended that the antenna pattern be designed based on the horizontal polarized omnidirectional pattern that facilitates the reception of strong signals especially in outdoor environments.
- Besides the module antennas, a laptop has other internal antennas, such as the WLAN antenna. Therefore, when designing the module antennas, the requirement on the isolation between module antennas and other laptop antennas should be considered. Ensure that proper distance is maintained between antennas if possible. To reduce the interference between antennas, it is recommended that an antenna is not designed close to another one.
- Carefully design the metallic components (such as the external frame of the metallic shell) in and near the antenna area by considering the effects on the antenna performance (such as whether the frequency offset of the antenna occurs and whether the antenna pattern is deformed).

## 4.6 ESD Protection for the Antenna Interface



In practical application, pay attention to the ESD protection for the antenna interface of the EM820W module. Incorrect operation may result in permanent damage to the RF components.

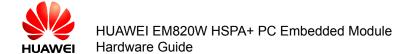
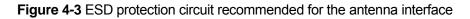
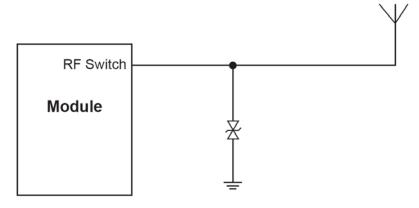


Figure 4-3 shows the ESD protection circuit recommended for the antenna interface.







It is recommended that you pay attention to the junction capacitance of the TVS diode when you choose the model of the TVS diode. Ensure that the junction capacitance of the TVS diode is lower than 1 pF.



## **5** Electrical and Reliability Features

## 5.1 About This Chapter

This chapter describes the electrical and reliability features of the interfaces in the EM820W module, including:

- Extreme Working Conditions
- Working and Storage Temperatures and Humidity
- Electrical Criteria of Application Interfaces
- Power Supply Features
- Reliability Features
- EMC and ESD Features

## **5.2 Extreme Working Conditions**



Table 5-1 lists the extreme working conditions for the EM820W module. Using the EM820W module beyond these conditions may result in permanent damage to the module.

## 5.3 Working and Storage Temperatures and Humidity

Table 5-1 lists the working and storage temperatures and humidity for the EM820W module.



| Specification                      | Minimum Value | Maximum Value | Unit |
|------------------------------------|---------------|---------------|------|
| Normal working<br>temperatures [1] | -10           | +55           | °C   |
| Extreme working temperatures [2]   | –20 to –10    | +55 to +70    | °C   |
| Ambient temperature for storage    | -40           | +85           | °C   |
| Moisture                           | 5             | 95            | %    |

 Table 5-1 Working and storage temperatures and humidity for the EM820W module

#### 

[1]: When the EM820W module works at this temperature, all its RF indexes comply with the 3GPP TS 45.005 specifications.

[2]: When the EM820W module works at this temperature, certain RF indexes do not comply with the 3GPP TS 45.005 specifications.

## **5.4 Electrical Criteria of Application Interfaces**

Table 5-2 lists electrical features (typical values)

| Parameter       | Description                  | Minimum Value            | Maximum Value            | Unit |
|-----------------|------------------------------|--------------------------|--------------------------|------|
| V <sub>IH</sub> | High-level input<br>voltage  | 0.65*V <sub>DD_PX</sub>  | V <sub>DD_PX</sub> +0.3  | V    |
| V <sub>IL</sub> | Low-level input voltage      | -0.3                     | 0.35* V <sub>DD_PX</sub> | V    |
| <sub>leak</sub> | Input leakage current        | -0.2                     | 0.2                      | uA   |
| V <sub>OH</sub> | High-level<br>output voltage | V <sub>DD_PX</sub> -0.45 | V <sub>DD_PX</sub>       | V    |
| V <sub>OL</sub> | Low-level<br>output voltage  | 0                        | 0.45                     | V    |
| I <sub>OH</sub> | High-level<br>output current | 1.5                      | -                        | mA   |
| I <sub>OL</sub> | Low-level output current     | -                        | -1.5                     | mA   |

Table 5-2 Electrical features of application interfaces



## **5.5 Power Supply Features**

## 5.5.1 Power Supply

The EM820W receives its power supply from a 3.3 V power source, which must satisfy all requirements of PCI Express Mini CEM specifications, such as voltage tolerance and peak and normal current. The detailed requirements are listed in Table 5-3.

| Table 5-3 Power require |
|-------------------------|
|-------------------------|

| Power | Voltage Tolerance | Peak (Maximum) | Normal (Maximum) |
|-------|-------------------|----------------|------------------|
| 3.3 V | ±9%               | 2750 mA        | 1100 mA          |

#### 

In burst transmit mode of GSM/GPRS/EDGE, the instantaneous current of the module will exceed 2.75 A, which will pull down the power voltage transitorily and perhaps result in the reset of the module or host. In order to prevent this situation, you can add a large bulk capacitor beside the module on the host side (at least two 330uF capacitors).

## 5.5.2 Power Consumption

The power consumptions of the EM820W in different scenarios are listed in Table 5-4, Table 5-5 and Table 5-6 respectively.

| Description | Band          | Test Value | Units | Power (dBm)     |
|-------------|---------------|------------|-------|-----------------|
| WCDMA       | Band I 284 mA |            | mA    | 1 dBm Tx Power  |
|             |               | 336        |       | 10 dBm Tx Power |
|             |               | 544        |       | 24 dBm Tx Power |
|             | Band II       | 289        | mA    | 1 dBm Tx Power  |
|             |               | 340        |       | 10 dBm Tx Power |
|             |               | 606        |       | 24 dBm Tx Power |
|             | Band V        | 293        | mA    | 1 dBm Tx Power  |
|             |               | 317        |       | 10 dBm Tx Power |
|             |               | 501        |       | 24 dBm Tx Power |
|             | Band VIII     | 291        | mA    | 1 dBm Tx Power  |
|             |               | 310        |       | 10 dBm Tx Power |
|             |               | 517        |       | 24 dBm Tx Power |

Table 5-4 DC power consumption (HSPA/WCDMA)



| Description | Band      | Test Value | Units   | Power (dBm)     |  |
|-------------|-----------|------------|---|-----------------|--|
| HSDPA       | Band I    | 348        | mA  | 1 dBm Tx Power  |  |
|             |           | 395        |   | 10 dBm Tx Power |  |
|             |           | 585        |   | 24 dBm Tx Power |  |
|             | Band II   | 350        | mA  | 1 dBm Tx Power  |  |
|             |           | 409        |   | 10 dBm Tx Power |  |
|             |           | 646        | mA       1 dBm Tx Power         10 dBm Tx Power       24 dBm Tx Power         mA       1 dBm Tx Power         10 dBm Tx Power       10 dBm Tx Power         10 dBm Tx Power       10 dBm Tx Power         mA       1 dBm Tx Power         10 dBm Tx Power       10 dBm Tx Power         mA       1 dBm Tx Power         10 dBm Tx Power       10 dBm Tx Power         mA       1 dBm Tx Power         10 dBm Tx Power       10 dBm Tx Power         mA       1 dBm Tx Power         10 dBm Tx Power       10 dBm Tx Power         mA       1 dBm Tx Power         mA       1 dBm Tx Power         10 dBm Tx Power       10 dBm Tx Power         mA       1 dBm Tx Power         10 dBm Tx Power       10 dBm Tx Power         mA       1 dBm Tx Power         10 dBm Tx Power       10 dBm Tx Power         mA       1 dBm Tx Power         10 dBm Tx Power       10 dBm Tx Power         mA       1 dBm Tx Power         10 dBm Tx Power       10 dBm Tx Power         mA       1 dBm Tx Power         mA       1 dBm Tx Power |                 |  |
|             | Band V    | 361        | mA  | 1 dBm Tx Power  |  |
|             |           | 380        |   | 10 dBm Tx Power |  |
|             |           | 552        |   | 24 dBm Tx Power |  |
|             | Band VIII | 343        | mA  | 1d Bm Tx Power  |  |
|             |           | 365        |   | 10 dBm Tx Power |  |
|             |           | 560        |   | 24 dBm Tx Power |  |
| HSUPA       | Band I    | 378        | mA  | 1 dBm Tx Power  |  |
|             |           | 424        |   | 10 dBm Tx Power |  |
|             |           | 610        |   | 24 dBm Tx Power |  |
|             | Band II   | 357        | mA  | 1 dBm Tx Power  |  |
|             |           | 407        |   | 10 dBm Tx Power |  |
|             |           | 643        |   | 24 dBm Tx Power |  |
|             | Band V    | 363        | mA  | 1 dBm Tx Power  |  |
|             |           | 381        |   | 10 dBm Tx Power |  |
|             |           | 524        |   | 24 dBm Tx Power |  |
|             | Band VIII | 361        | mA  | 1d Bm Tx Power  |  |
|             |           | 382        |   | 10 dBm Tx Power |  |
|             |           | 531        |   | 24 dBm Tx Power |  |

#### Table 5-5 DC power consumption (GSM/GPRS/EDGE)

| Description | Test Value | Units | PCL | Configuration |
|-------------|------------|-------|-----|---------------|
| GPRS850     | 346        | mA    | 5   | 1 Up/1 Down   |
|             | 513        |       |     | 2 Up/1 Down   |
|             | 160        | mA    | 15  | 1 Up/1 Down   |



| Description | Test Value | Units | PCL | Configuration |
|-------------|------------|-------|-----|---------------|
|             | 225        |       |     | 2 Up/1 Down   |
| GPRS900     | 345        | mA    | 5   | 1 Up/1 Down   |
|             | 514        |       |     | 2 Up/1 Down   |
|             | 143        | mA    | 15  | 1 Up/1 Down   |
|             | 195        |       |     | 2 Up/1 Down   |
| GPRS1800    | 236        | mA    | 0   | 1 Up/1 Down   |
|             | 355        |       |     | 2 Up/1 Down   |
|             | 128        | mA    | 10  | 1 Up/1 Down   |
|             | 166        |       |     | 2 Up/1 Down   |
| GPRS1900    | 217        | mA    | 0   | 1 Up/1 Down   |
|             | 318        |       |     | 2 Up/1 Down   |
|             | 131        | mA    | 10  | 1 Up/1 Down   |
|             | 167        |       |     | 2 Up/1 Down   |
| EDGE850     | 250        | mA    | 8   | 1 Up/1 Down   |
|             | 351        |       |     | 2 Up/1 Down   |
|             | 488        |       |     | 4 Up/1 Down   |
|             | 165        | mA    | 15  | 1 Up/1 Down   |
|             | 217        |       |     | 2 Up/1 Down   |
|             | 293        |       |     | 4 Up/1 Down   |
| EDGE900     | 229        | mA    | 8   | 1 Up/1 Down   |
|             | 329        |       |     | 2 Up/1 Down   |
|             | 468        |       |     | 4 Up/1 Down   |
|             | 142        | mA    | 15  | 1 Up/1 Down   |
|             | 193        |       |     | 2 Up/1 Down   |
|             | 270        |       |     | 4 Up/1 Down   |
| EDGE1800    | 192        | mA    | 2   | 1 Up/1 Down   |
|             | 265        |       |     | 2 Up/1 Down   |
|             | 362        |       |     | 4 Up/1 Down   |
|             | 128        | mA    | 10  | 1 Up/1 Down   |
|             | 165        |       |     | 2 Up/1 Down   |
|             | 210        |       |     | 4 Up/1 Down   |



| Description | Test Value | Units | PCL | Configuration |
|-------------|------------|-------|-----|---------------|
| EDGE1900    | 194        | mA    | 2   | 1 Up/1 Down   |
|             | 257        |       |     | 2 Up/1 Down   |
|             | 341        |       |     | 4 Up/1 Down   |
|             | 142        | mA    | 10  | 1 Up/1 Down   |
|             | 177        |       |     | 2 Up/1 Down   |
|             | 218        |       |     | 4 Up/1 Down   |

#### Table 5-6 DC power consumption(Idle and Suspend)

| Scenario                          | Idle               |                     | Suspend            |                     |      |
|-----------------------------------|--------------------|---------------------|--------------------|---------------------|------|
|                                   | Offline<br>Enabled | Offline<br>Disabled | Offline<br>Enabled | Offline<br>Disabled | Unit |
| WCDMA 2100MHz<br>DRX = 8 (2.56 s) | 66.3               | 72.7                | 4.1                | 5.8                 | mA   |
| GSM 900MHz<br>MFRM = 5 (1.18 s)   | 70.6               | 73.1                | 4.1                | 7.8                 | mA   |

#### 

- In idle mode, the module is registered to the network, USB bus is active, and no voice or data call connection is ongoing.
- The above values are the average of some test samples.

## **5.6 Reliability Features**

Table 5-7 lists the test conditions and results of the mechanical reliability of the EM820W module.

| Table 5-7 | Test co | onditions | and r | esults | of the | mechanical | reliability | of the | EM820W | module |
|-----------|---------|-----------|-------|--------|--------|------------|-------------|--------|--------|--------|
|-----------|---------|-----------|-------|--------|--------|------------|-------------|--------|--------|--------|

| Item                     | Test Condition                              | Standard |
|--------------------------|---|----------|
| Low-temperature storage  | Temperature: -40±2°C<br>Test duration: 24 h | IEC60068 |
| High-temperature storage | Temperature: 85±2°C<br>Test duration: 24 h  | IEC60068 |



| Item                        | Test Condition   | Standard |
|-----------------------------|--|----------|
| Low-temperature<br>working  | Temperature: –30±2°C<br>Test duration: 24 h  | IEC60068 |
| High-temperature<br>working | Temperature: 75±2°C<br>Test duration: 24 h   | IEC60068 |
| Damp heat cycling           | High temperature: 55±2°C<br>Low temperature: 25±2°C<br>Humidity: 95%<br>Repetition times: 4<br>Test duration: 12 h + 12 h  | IEC60068 |
| Temperature shock           | Low temperature: -40±2°C<br>High temperature: 85±2°C<br>Temperature change interval: < 30s<br>Test duration: 15 min<br>Repetition times: 100                             | IEC60068 |
| Salty fog test              | Temperature: 35°C<br>Density of the NaCl solution: 5±1%<br>Spraying interval: 8 h<br>Duration of exposing the module to<br>the temperature of 35°C: 16 h                 | IEC60068 |
| Sine vibration              | Frequency range: 5 Hz to 200 Hz<br>Acceleration: 10 m/s2<br>Frequency scan rate: 1 oct/min<br>Test period: 3 axial directions. Five<br>circles for each axial direction. | IEC60068 |
| Shock test                  | Half-sine wave shock<br>Peak acceleration: 300 m/s2<br>Shock duration: 11 ms<br>Test period: 6 axial directions. One<br>shock for each axial direction.                  | IEC60068 |
| Clash test                  | Half-sine wave<br>Peak acceleration: 180 m/s2<br>Pulse duration: 6 ms<br>Repetition time: 6 directions. 1000<br>times for each direction.                                | IEC60068 |



| Item      | Test Condition   | Standard |
|-----------|--|----------|
| Drop test | First case: 0.3 m in height. Drop the<br>EM820W module on the marble<br>terrace with one surface facing<br>downwards twice. Six surfaces<br>should be tested.  | IEC60068 |
|           | Second case: 0.8 m in height. Drop<br>the EM820W module on the marble<br>terrace with one surface facing<br>downwards twice. Six surfaces<br>should be tested. |          |

# 5.7 EMC and ESD Features

EMC tests have to be performed on the application as soon as possible to detect any potential problems.

When designing, special attention should be paid to:

- Possible spurious emissions radiated by the application to the RF receiver in the receiver band.
- ESD protection that is mandatory on all signals which are externally accessible Typically, ESD protection is mandatory for the:
  - SIM (if accessible from outside)
  - Serial link
- Length of the SIM interface lines (preferably <10cm).
- EMC protection on audio input/output (filters against 900MHz emissions).
- Biasing of the microphone inputs.
- Ground plane: HUAWEI Wireless recommends a common ground plane for analog/digital/RF grounds.
- A metallic case or plastic casing with conductive paint is recommended, except for areas around the antenna.

#### 

The HUAWEI EM820W Embedded Module does not include any protection against high voltage.



# **6** Mechanical Specifications

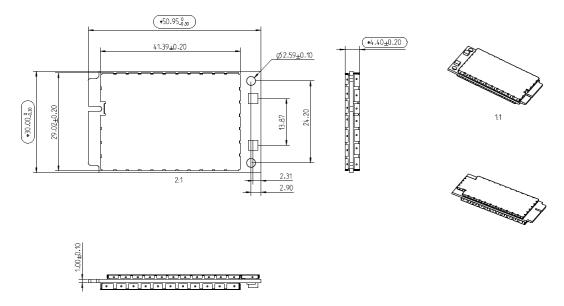
# 6.1 Dimensions and Interfaces

## 6.1.1 Dimensions and Interfaces of EM820W

The dimensions of EM820W are 50.95 mm (length)  $\times$  30 mm (width)  $\times$  4.5 mm (height). Figure 6-1 shows the dimensions of EM820W in detail.

Figure 6-1 shows the appearance of the interfaces on the EM820W.

#### Figure 6-1 Dimensions of the EM820W



## 6.2 Dimensions of the Mini PCI Express Connector

The EM820W adopts a standard Mini PCI Express connector that has 52 pins and complies with the *PCI Express Mini Card Electromechanical Specification Revision 1.2*.

Issue 01 (2010-12-31)

Huawei Proprietary and Confidential Copyright © Huawei Technologies Co., Ltd.

Figure 6-2 shows a 52-pin Mini PCI Express connector (take the Molex 67910002 as an example).

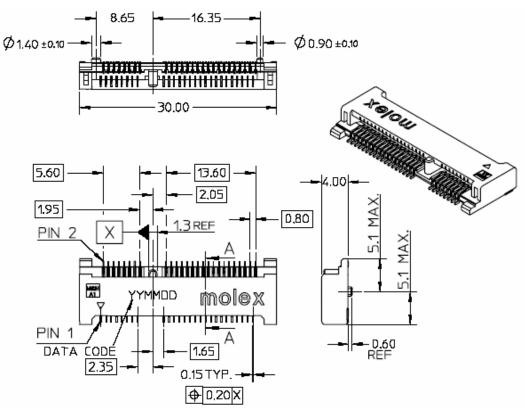


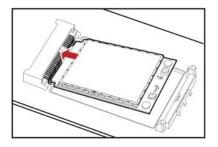
Figure 6-2 Dimensions of the Mini PCI Express connector

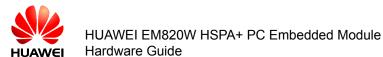
# 6.3 Specification Selection for Fasteners

### 6.3.1 Installing the EM820W on the Main Board of PC

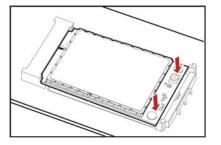
To install the EM820W on the main board of the PC, do the following:

Step 1 Insert the Mini PCI Express connector of the EM820W into the WWAN Mini PCI Express interface on the main board of PC.

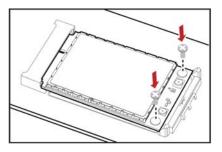




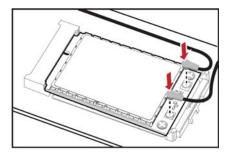
Step 2 Press downwards to fix the EM820W in the module slot.



Step 3 Use a screwdriver to fix the EM820W on the main board of the PC with two screws provided in the EM820W packing box.

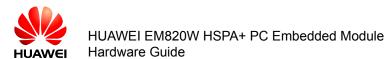


Step 4 Insert the connector of the main antenna into the MAIN antenna interface (M) of the EM820W according to the indication on the label of the EM820W. Insert the connector of the auxiliary antenna into the AUX antenna interface (A) of the c EM820W in the same way.



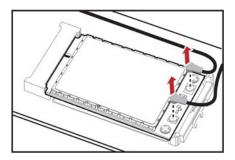
### 

- Insert the antenna connectors vertically into the antenna interfaces of the EM820W.
- Do not press or squeeze the antenna cable or damage the connectors. Otherwise, the wireless performance of the EM820W may be reduced or the EM820W cannot work normally.
- Ensure that the antenna cables are routed through the channel in the frame of the PC and do not lay the cables across the raised edges of the frame.

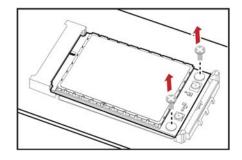


## 6.3.2 Romoving the EM820W from the Main Board of PC

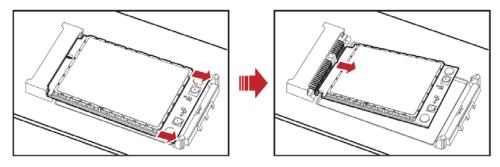
Step 1 Disconnect the antenna cables from the EM820W. You can lift the connectors using a small screwdriver.



Step 2 Remove the two screws with the screwdriver.



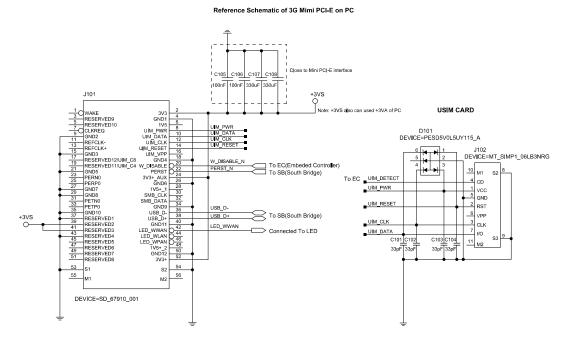
Step 3 Slide backwards the two clips to release the EM820W from the slot. Then, lift up the EM820W.





# **7** Appendix A Circuits of Typical Interfaces







# 8 Appendix B Acronyms and Abbreviations

| Acronym or Abbreviation | Expansion  |
|-------------------------|--|
| BB                      | Baseband   |
| CE                      | European Conformity  |
| CS                      | Coding Scheme  |
| CSD                     | Circuit Switched Data                                      |
| DC                      | direct current   |
| DCE                     | data circuit-terminating equipment                         |
| DMA                     | direct memory access                                       |
| DTE                     | data terminal equipment                                    |
| EIA                     | Electronic Industries Association                          |
| EMC                     | electromagnetic compatibility                              |
| ESD                     | electrostatic discharge                                    |
| EU                      | European Conformity  |
| FCC                     | Federal Commnications Commission                           |
| FDD-TDMA                | frequency division duplexing-time division multiple access |
| GMSK                    | Gaussian minimum shift keying                              |
| GPRS                    | general packet radio service                               |
| ISO                     | International Standards Organization                       |
| LCP                     | liquid crystal polyester                                   |
| LDO                     | low-dropout  |
| LED                     | light-emitting diode                                       |
| МСР                     | multi-chip package   |

Huawei Proprietary and Confidential Copyright © Huawei Technologies Co., Ltd.



| Acronym or Abbreviation | Expansion  |
|-------------------------|--|
| NTC                     | negative temperature coefficient                       |
| РВССН                   | Packet Broadcast Control Channel                       |
| РСВ                     | printed circuit board                                  |
| PDU                     | protocol data unit                                     |
| PMU                     | Power manage Unit                                      |
| RF                      | radio frequency  |
| RoHS                    | Restriction of the use of certain Hazardous Substances |
| RTC                     | real-time clock  |
| SIM                     | Subscriber Identity Module                             |
| TTL                     | transistor-transistor logic                            |
| TVS                     | transient voltage suppressor                           |
| VSWR                    | voltage standing wave ratio                            |

Free Manuals Download Website <u>http://myh66.com</u> <u>http://usermanuals.us</u> <u>http://www.somanuals.com</u> <u>http://www.4manuals.cc</u> <u>http://www.4manuals.cc</u> <u>http://www.4manuals.cc</u> <u>http://www.4manuals.com</u> <u>http://www.404manual.com</u> <u>http://www.luxmanual.com</u> <u>http://aubethermostatmanual.com</u> Golf course search by state

http://golfingnear.com Email search by domain

http://emailbydomain.com Auto manuals search

http://auto.somanuals.com TV manuals search

http://tv.somanuals.com